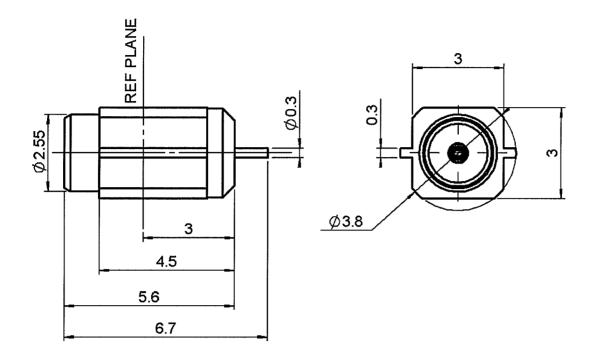
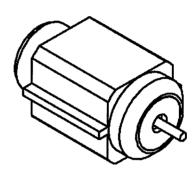
R199.005.801

Series: MC-CARD







All dimensions are in mm.

COMPONENTS	MATERIALS	PLATINGS (µm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BERYLLIUM COPPER - PTFE	GOLD 0.2 OVER NICKEL 2 GOLD 0.8 OVER NICKEL 2

Issue: 0420 E



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PACKAGING

Standard Unit Other 1800 'W' option Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance

50 Ω

Frequency

0-8 GHz

VSWR Insertion loss 1.15 + 0

- (

0.015 x F(GHz) Maxi **.07** √F(GHz) dB Maxi

RF leakage

- - F(GHz)) dB Maxi
170 Veff Maxi

Voltage rating Dielectric withstanding voltage Insulation resistance

500 Veff mini **5000** MΩ mini

ENVIRONMENTAL

Operating temperature

-65/+165 ° C

Hermetic seal

NA Atm.cm3/s

Panel leakage

NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end

10 N mini

Axial force – Opposite end

10 N mini

Torque

NA N.cm mini

Recommended torque

Mating

NA N.cm

Panel nut

NA N.cm

Mating life

5000 Cycles mini

Weight

0.270 g

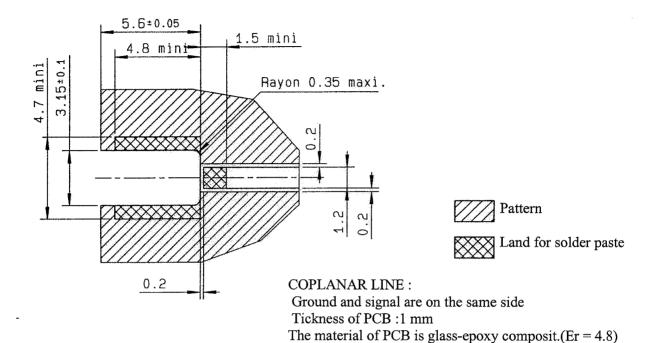
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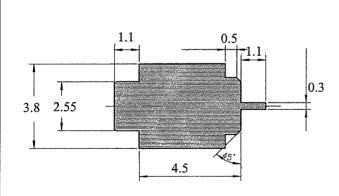
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INFORMATIONS



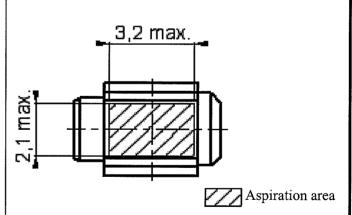
pattern on the PCB.

SHADOW OF RECEPTACLE FOR VIDEO CAMERA



ASPIRATION AREA

The solder resist should be printed except for the land

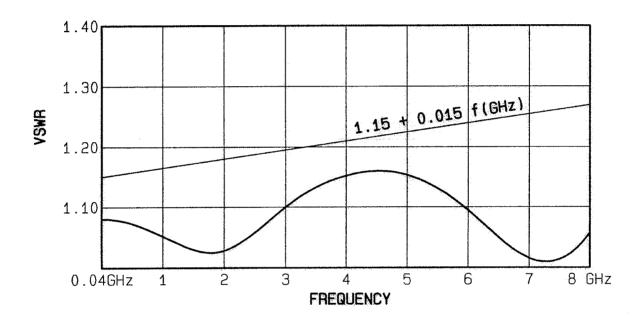




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R199 005 504 CONNECTED WITH R199 005 200



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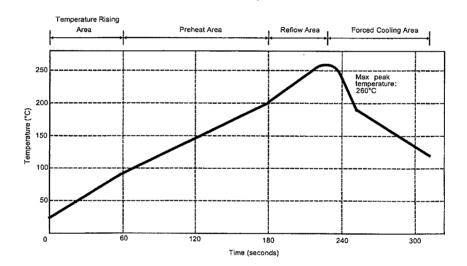
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SOLDER PROCEDURE

- 1. Deposition of solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 microns (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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MC-CARD SERIES INFORMATION

